

CLAIMS

What is claimed is:

1. A device comprising:
a component; and
5 a heat sink attached to the component, the heat sink having at least one cutout, and
the heat sink extending beyond more than two sides of the component.
2. The device of claim 1, further comprising a clip in contact with the component
and the heat sink, the clip holding the component in contact with the heat sink.
- 10 3. The device of claim 2, wherein the clip comprises a protruding portion that
extends through the cutout.
4. The device of claim 3, wherein the protruding portion comprises a plate.
- 15 5. The device of claim 3, wherein the protruding portion comprises a rod.
6. The device of claim 2, wherein the cutout comprises a hole shaped to fit a
protruding portion of the clip.
- 20 7. The device of claim 2, wherein at least one of the at least one cutout comprises a
slit shaped to fit a plate protruding from the clip, wherein the length of the slit is
substantially equal to the length of the longest side of the plate.
- 25 8. The device of claim 1, wherein the cutout is located on an edge of the heat sink.
9. A method of fastening a heat sink to a component, the method comprising
extending a protruding portion of a clip through a cutout in the heat sink, the cutout being
located such that the heat sink extends beyond more than two edges of the component
30 when the component is in contact with the heat sink.

10. The method of claim 9, wherein the component is smaller than the heat sink and fastened close to the center of the heat sink.

5 11. The method of claim 9, wherein the cutout is located along an edge of the heat sink.

12. The method of claim 9, wherein the clip comprises a polygonal frame and each straight edge of the polygonal frame has a protruding portion.

10 13. The method of claim 9, further comprising extending the protruding portion of a clip through a cutout in the motherboard.

14. A device comprising:
a component;

a heat sink attached to the component, the heat sink having at least one cutout and having an overhang on all sides of the component; and

a clip in contact with the component and the heat sink, the clip having a polygonal frame and a protruding portion that extends through the at least one cutout, the protruding portion attaching the component to the heat sink.

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15. A device comprising:
a component;

a heat sink attached to the component, the heat sink having at least one cutout and having an overhang on all sides of the component; and

25 a clip, the clip having a polygonal frame in contact with the heat sink and a protruding portion that extends through the at least one cutout, the protruding portion attaching the heat sink to a motherboard so that the component is fixed in a location between the motherboard and the component.